



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC057N08NS3 G		<b>Issued</b>		19. July 2018	
<b>MA#</b>				MA001509956					
<b>Package</b>				PG-TDSON-8-39		<b>Weight*</b>		121.30 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.666	3.02	3.02	30224	30224	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		312		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94		
	non noble metal	copper	7440-50-8	37.762	31.13	31.17	311298	311704	
wire	non noble metal	copper	7440-50-8	0.066	0.05	0.05	540	540	
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		666		
	plastics	epoxy resin	-	6.387	5.26		52649		
	inorganic material	silicondioxide	60676-86-0	33.954	27.99	33.32	279907	333222	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	11967	11967	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1365	1365	
solder	noble metal	silver	7440-22-4	0.076	0.06		626		
	non noble metal	tin	7440-31-5	0.061	0.05		501		
	non noble metal	lead	7439-92-1	2.899	2.39	2.50	23902	25029	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.33	9.34	93319	93440	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		184		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	noble metal	silver	7440-22-4	1.032	0.85		8504		
	non noble metal	copper	7440-50-8	22.292	18.38	19.26	183766	192509	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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